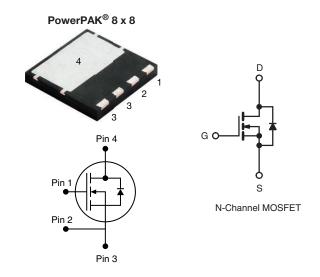
HALOGEN FREE

## **E Series Power MOSFET**

PRODUCT SUMMARY					
V <sub>DS</sub> (V) at T <sub>J</sub> max.	650				
R <sub>DS(on)</sub> typ. (Ω) at 25 °C	V <sub>GS</sub> = 10 V 0.117				
Q <sub>g</sub> max. (nC)	116				
Q <sub>gs</sub> (nC)	18				
Q <sub>gd</sub> (nC)	33				
Configuration	Single				



#### **FEATURES**

- Fully lead (Pb)-free device
- Low figure-of-merit (FOM) Ron x Qg
- Low input capacitance (Ciss)
- · Reduced switching and conduction losses
- Ultra low gate charge (Q<sub>q</sub>)
- Avalanche energy rated (UIS)
- · Kelvin connection for reduced gate noise
- Material categorization: for definitions of compliance please see <a href="https://www.vishay.com/doc?99912"><u>www.vishay.com/doc?99912</u></a>

#### **APPLICATIONS**

- Server and telecom power supplies
- Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- Lighting
  - High-intensity discharge (HID)
  - Fluorescent ballast lighting
- Industrial
  - Welding
  - Induction heating
  - Motor drives
  - Battery chargers
  - Renewable energy
  - Solar (PV inverters)

ORDERING INFORMATION	
Package	PowerPAK 8 x 8
Lead (Pb)-free and Halogen-free	SiHH26N60E-T1-GE3

ABSOLUTE MAXIMUM RATINGS (	T <sub>C</sub> = 25 °C, unle	ess otherwis	se noted)		
PARAMETER			SYMBOL	LIMIT	UNIT
Drain-Source Voltage			V <sub>DS</sub>	600	V
Gate-Source Voltage			$V_{GS}$	± 30	7 °
Continuous Drain Current (T, = 150 °C)	V <sub>GS</sub> at 10 V	T <sub>C</sub> = 25 °C	- I <sub>D</sub>	25	
Continuous Drain Current (1) = 150 C)	V <sub>GS</sub> at 10 V	T <sub>C</sub> = 100 °C		16	Α
Pulsed Drain Current a			I <sub>DM</sub>	50	
Linear Derating Factor				1.6	W/°C
Single Pulse Avalanche Energy <sup>b</sup>			E <sub>AS</sub>	353	mJ
Maximum Power Dissipation			P <sub>D</sub>	202	W
Operating Junction and Storage Temperature Range			T <sub>J</sub> , T <sub>stg</sub>	-55 to +150	°C
Drain-Source Voltage Slope T <sub>J</sub> = 125 °C			dV/dt	37	V/ns
Reverse Diode dV/dt <sup>c</sup>				20	) v/ns

## Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature.
- b.  $V_{DD}$  = 140 V, starting  $T_J$  = 25 °C, L = 28.2 mH,  $R_g$  = 25  $\Omega$ ,  $I_{AS}$  = 5 A.
- c.  $I_{SD} \le I_D$ ,  $dI/dt = 100 \text{ A/}\mu\text{s}$ , starting  $T_J = 25 \,^{\circ}\text{C}$ .



THERMAL RESISTANCE RATINGS					
PARAMETER SYMBOL TYP. MAX. UNI					
Maximum Junction-to-Ambient	$R_{thJA}$	38	50	°C/W	
Maximum Junction-to-Case (Drain)	$R_{thJC}$	0.48	0.62	C/VV	

PARAMETER	SYMBOL	TES	MIN.	TYP.	MAX.	UNIT	
Static							
Drain-Source Breakdown Voltage	$V_{DS}$	V <sub>GS</sub> =	: 0 V, I <sub>D</sub> = 250 μA	600	-	-	V
V <sub>DS</sub> Temperature Coefficient	$\Delta V_{DS}/T_{J}$	Referenc	e to 25 °C, I <sub>D</sub> = 1 mA	-	0.67	-	V/°C
Gate-Source Threshold Voltage (N)	V <sub>GS(th)</sub>	V <sub>DS</sub> =	V <sub>GS</sub> , I <sub>D</sub> = 250 μA	2	-	4	V
Coto Courso Lockego	I <sub>GSS</sub>	,	$V_{GS} = \pm 20 \text{ V}$		-	± 100	nA
Gate-Source Leakage		,	$I_{GS} = \pm 30 \text{ V}$	-	-	± 1	μΑ
Zava Cata Valtaga Dvain Cuwant		V <sub>DS</sub> =	600 V, V <sub>GS</sub> = 0 V	-	-	1	μA
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = 480 V	, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 125 °C	-	-	50	
Drain-Source On-State Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V	I <sub>D</sub> = 13 A	-	0.117	0.135	Ω
Forward Transconductance	9 <sub>fs</sub>	V <sub>DS</sub>	= 30 V, I <sub>D</sub> = 13 A	-	8.6	-	S
Dynamic							
Input Capacitance	C <sub>iss</sub>		V <sub>GS</sub> = 0 V,	-	2815	-	
Output Capacitance	C <sub>oss</sub>	Ţ,	$V_{\rm DS} = 100  \rm V$	-	125	-	
Reverse Transfer Capacitance	C <sub>rss</sub>		f = 1 MHz	-	7	-	
Effective Output Capacitance, Energy Related <sup>a</sup>	C <sub>o(er)</sub>	V <sub>DS</sub> = 0 V to 480 V, V <sub>GS</sub> = 0 V		-	124	-	pF
Effective Output Capacitance, Time Related <sup>b</sup>	C <sub>o(tr)</sub>			-	381	-	
Total Gate Charge	Qg			-	77	116	
Gate-Source Charge	Q <sub>gs</sub>	$V_{GS} = 10 \text{ V}$ $I_D = 13 \text{ A}, V_{DS} = 480 \text{ V}$		-	18	-	nC
Gate-Drain Charge	Q <sub>gd</sub>			-	33	-	
Turn-On Delay Time	t <sub>d(on)</sub>			-	28	56	
Rise Time	t <sub>r</sub>	V <sub>DD</sub> = 480 V, I <sub>D</sub> = 13 A,		-	54	81	]
Turn-Off Delay Time	t <sub>d(off)</sub>	V <sub>GS</sub> =	$10 \text{ V, R}_{g} = 9.1 \Omega$	-	80	120	ns -
Fall Time	t <sub>f</sub>			-	45	90	
Gate Input Resistance	R <sub>g</sub>	f = 1 MHz, open drain		0.2	0.5	1.1	Ω
<b>Drain-Source Body Diode Characteristic</b>	S						
Continuous Source-Drain Diode Current	I <sub>S</sub>	MOSFET sym showing the		-	-	25	
Pulsed Diode Forward Current	I <sub>SM</sub>	integral reverse p - n junction diode		-	-	50	A
Diode Forward Voltage	V <sub>SD</sub>	T <sub>J</sub> = 25 °C, I <sub>S</sub> = 13 A, V <sub>GS</sub> = 0 V		-	0.9	1.2	V
Reverse Recovery Time	t <sub>rr</sub>			-	459	918	ns
Reverse Recovery Charge	Q <sub>rr</sub>	$T_J = 25 ^{\circ}\text{C}, I_F = I_S = 13 \text{A},$		-	7.6	15.2	μC
Reverse Recovery Current	I <sub>RRM</sub>	dl/dt = 100 A/ $\mu$ s, V <sub>R</sub> = 25 V		_	28	_	A

### Notes

- a.  $C_{oss(er)}$  is a fixed capacitance that gives the same energy as  $C_{oss}$  while  $V_{DS}$  is rising from 0 % to 80 %  $V_{DS}$ .
- b.  $C_{oss(tr)}$  is a fixed capacitance that gives the same charging time as  $C_{oss}$  while  $V_{DS}$  is rising from 0 % to 80 %  $V_{DS}$ .



## TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

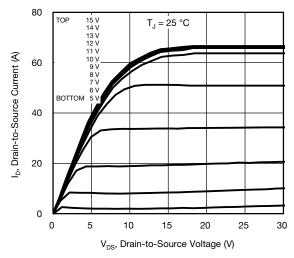


Fig. 1 - Typical Output Characteristics

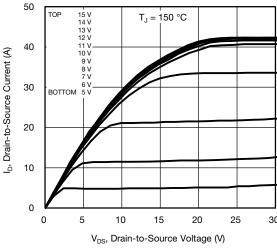


Fig. 2 - Typical Output Characteristics

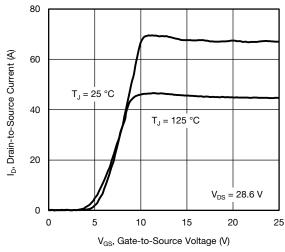


Fig. 3 - Typical Transfer Characteristics

S15-2032-Rev. B, 24-Aug-15

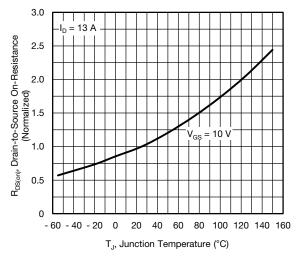


Fig. 4 - Normalized On-Resistance vs. Temperature

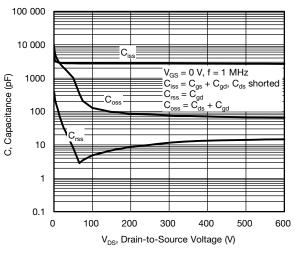


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

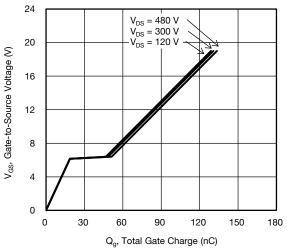


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage



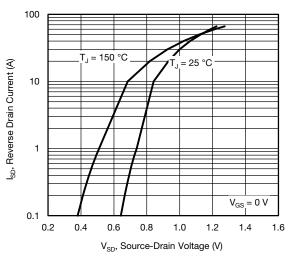


Fig. 7 - Typical Source-Drain Diode Forward Voltage

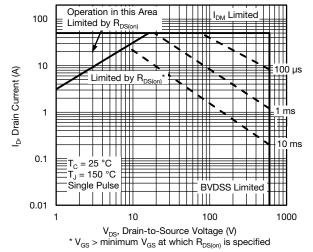


Fig. 8 - Maximum Safe Operating Area

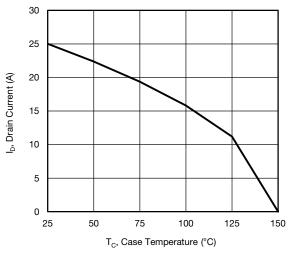


Fig. 9 - Maximum Drain Current vs. Case Temperature

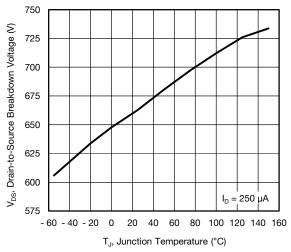


Fig. 10 - Temperature vs. Drain-to-Source Voltage

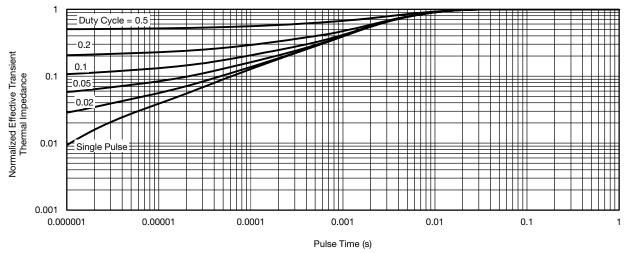


Fig. 11 - Normalized Thermal Transient Impedance, Junction-to-Case



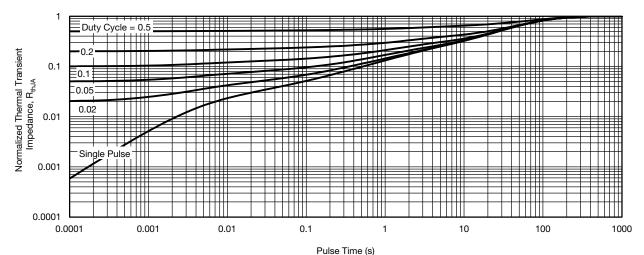


Fig. 12 - Normalized Thermal Transient Impedance, Junction-to-Ambient

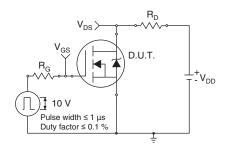


Fig. 13 - Switching Time Test Circuit

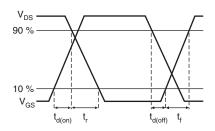


Fig. 14 - Switching Time Waveforms

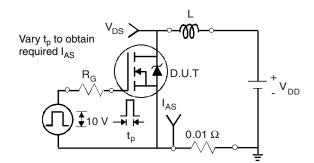


Fig. 15 - Unclamped Inductive Test Circuit

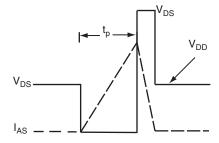


Fig. 16 - Unclamped Inductive Waveforms

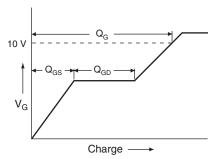


Fig. 17 - Basic Gate Charge Waveform

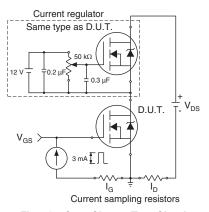
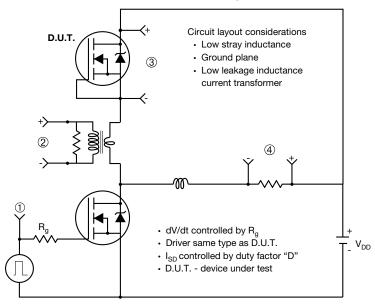


Fig. 18 - Gate Charge Test Circuit



## Peak Diode Recovery dV/dt Test Circuit



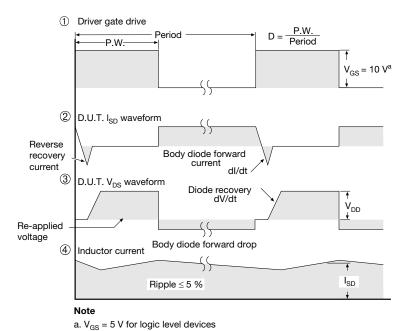
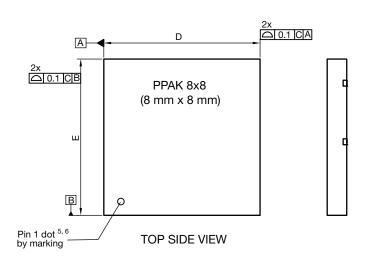
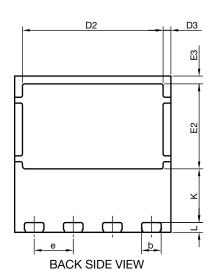


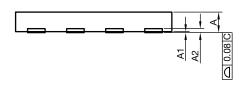
Fig. 19 - For N-Channel

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# PowerPAK® 8 x 8 Case Outline







DIM.		MILLIMETERS		INCHES				
DINI.	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.		
A 8	0.95	1.00	1.05	0.037	0.039	0.041		
A1	0.00	-	0.05	0.000	-	0.002		
A2		020 ref.			0.008 ref.			
b <sup>4</sup>	0.95	1.00	1.05	0.037	0.039	0.041		
D	7.90	8.00	8.10	0.311	0.315	0.319		
D2	7.10	7.20	7.30	0.280	0.283	0.287		
D3		0.40 BSC			0.016 BSC			
е	2.00 BSC		0.079 BSC					
E	7.90	8.00	8.10	0.311	0.315	0.319		
E2	4.30	4.35	4.40	0.169	0.171	0.173		
E3	0.40 BSC			0.40 BSC 0.016 BSC				
K	2.75 BSC		0.108 BSC					
L	0.45	0.50	0.55	0.018	0.020	0.022		
N <sup>3</sup>	8				8			

#### Notes

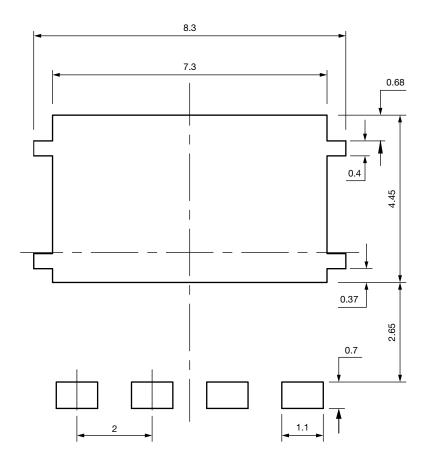
- 1. Use millimeters as the primary measurement.
- 2. Dimensioning and tolerances conform to ASME Y14.5 M 1994.
- 3. N is the number of terminals.
- 4. Package warpage max. 0.08 mm.
- 5. The pin 1 identifier must be existed on the top surface of the package by using indentation mark or other feature of package body.
- 6. Exact shape and size of this feature is optional.

ECN: T15-0225-Rev. A, 18-May-15

DWG: 6041

Revision: 18-May-15 1 Document Number: 67859

# Recommended Minimum PADs for PowerPAK® 8 mm x 8 mm



Dimensions in millimeters



Vishay

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